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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/829,583	04/22/2004	Hsuch-Chung Chen	252011-2240	6746	
47390	7590 05/19/2006		EXAMINER		
THOMAS, KAYDEN, HOSTEMEYER & RISLEY LLP			ANDUJAR, LEONARDO		
SUITE 1750			ART UNIT	PAPER NUMBER	
ATLANTA, (			2826		

DATE MAILED: 05/19/2006

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)				
	10/829,583	CHEN ET AL.				
Office Action Summary	Examiner	Art Unit				
	Leonardo Andújar	2826				
The MAILING DATE of this communication app Period for Reply	pears on the cover sheet with the c	orrespondence address				
A SHORTENED STATUTORY PERIOD FOR REPL THE MAILING DATE OF THIS COMMUNICATION.  - Extensions of time may be available under the provisions of 37 CFR 1.1 after SIX (6) MONTHS from the mailing date of this communication.  - If the period for reply specified above is less than thirty (30) days, a repl If NO period for reply is specified above, the maximum statutory period Failure to reply within the set or extended period for reply will, by statute Any reply received by the Office later than three months after the mailin earned patent term adjustment. See 37 CFR 1.704(b).	I36(a). In no event, however, may a reply be tin by within the statutory minimum of thirty (30) day will apply and will expire SIX (6) MONTHS from e, cause the application to become ABANDONE	nely filed s will be considered timely. the mailing date of this communication. D (35 U.S.C. § 133).				
Status						
1) Responsive to communication(s) filed on 03/2	0/2006.					
	s action is non-final.					
3) Since this application is in condition for allowa	nce except for formal matters, pro	secution as to the merits is				
closed in accordance with the practice under Ex parte Quayle, 1935 C.D. 11, 453 O.G. 213.						
Disposition of Claims						
4) ⊠ Claim(s) 1-12 and 14-21 is/are pending in the 4a) Of the above claim(s) is/are withdra 5) □ Claim(s) is/are allowed. 6) ⊠ Claim(s) 1-12 and 14-21 is/are rejected. 7) ⊠ Claim(s) is/are objected to. 8) □ Claim(s) are subject to restriction and/or	wn from consideration.					
Application Papers						
9) The specification is objected to by the Examine 10) The drawing(s) filed on <u>06 October 2005</u> is/are Applicant may not request that any objection to the Replacement drawing sheet(s) including the correct 11) The oath or declaration is objected to by the Examine	e: a) accepted or b) objected or b)	e 37 CFR 1.85(a). jected to. See 37 CFR 1.121(d).				
Priority under 35 U.S.C. § 119						
<ul> <li>12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).</li> <li>a) All b) Some * c) None of:</li> <li>1. Certified copies of the priority documents have been received.</li> <li>2. Certified copies of the priority documents have been received in Application No.</li> <li>3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).</li> <li>* See the attached detailed Office action for a list of the certified copies not received.</li> </ul>						
Attachment(s)  1) Notice of References Cited (PTO-892)  2) Notice of Draftsperson's Patent Drawing Review (PTO-948)  3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)  Paper No(s)/Mail Date	4) Interview Summary Paper No(s)/Mail D 5) Notice of Informal F 6) Other:					

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#### **DETAILED ACTION**

#### Continued Examination Under 37 CFR 1.114

1. A request for continued examination under 37 CFR 1.114, including the fee set forth in 37 CFR 1.17(e), was filed in this application after final rejection. Since this application is eligible for continued examination under 37 CFR 1.114, and the fee set forth in 37 CFR 1.17(e) has been timely paid, the finality of the previous Office action has been withdrawn pursuant to 37 CFR 1.114. Applicant's submission filed on 03/20/2006 has been entered.

## Claim Rejections - 35 USC § 112

- 2. The following is a quotation of the second paragraph of 35 U.S.C. 112:
  - The specification shall conclude with one or more claims particularly pointing out and distinctly claiming the subject matter which the applicant regards as his invention.
- 3. Claim 19 is rejected under 35 U.S.C. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.
- 4. Claim 19 recites the limitation "the distance" in line 1. There is insufficient antecedent basis for this limitation in the claim.

# Claim Rejections - 35 USC § 102

5. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States

of such treaty in the English language.

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- 6. Claims 1, 3-6, 8-12, 14, 15 and 17-21 are rejected under 35 U.S.C. 102(e) as being anticipated by Kunikiyo (US 6,717,267).
- 7. Regarding claim 1, Kunikiyo (e.g. fig. 12) shows a semiconductor configuration for dissipating heat away from a semiconductor device having a plurality of power bus lines, comprising: a semiconductor substrate 1, and a plurality of interconnect structures (26a/b, 20a) disposed on the substrate and in contact therewith and extending through the semiconductor device, the interconnect structures for dissipating heat through the substrate wherein the plurality of interconnection structures are disposed near a power line 72/28A/29A and wherein the plurality of lines are substantially enveloped in an insulating layer 23/10 (col. 9/lls. 1-6 & col. 21/lls. 40-50).
- 8. Regarding claim 3, Kunikiyo shows that the each of the plurality of interconnects structures comprises at least one via stack.
- 9. Regarding claim 4, Kunikiyo shows that the plurality of interconnects structures are close to the power line.
- 10. Regarding claim 5, Kunikiyo shows that at least one of the plurality of interconnect structure (26a, 26b) is joined to one other of the plurality of interconnect structures using a bridge structure
- 11. Regarding claim 6, Kunikiyo shows bridge structures (the section of 28A that joints the interconnections), each of the bridge structures joins a respective one of the plurality of interconnect structures (26a, 26b, 29a) to one other of the plurality of interconnect structures.

12. Regarding claims 8, 14, 17 and 19, Kunikiyo shows that the interconnect structures (26a, 26b) are alternatively spaced apart form each other by width of one of the interconnect structures (e.g. 29a).

- 13. Regarding claim 9, Kunikiyo shows that the plurality of interconnects structure (e.g. 26c and 26a) is alternatively spaced apart form a serpentine power line 25a by a distance (e.g. fig. 9).
- 14. Regarding claim 10, Kunikiyo shows that the distance is a width of one of the plurality of interconnect structures (e.g. 25a).
- 15. Regarding claim 11, Kunikiyo shows that each of the interconnect structures (21c) is spaced apart from a power line 19c by a distance (see fig. 13).
- 16. Regarding claim 12, Kunikiyo shows that the distance is the width of one of the plurality of interconnect structures (e.g. 21a).
- 17. Regarding claim 15, Kunikiyo shows that the ratio of width of one of the interconnect structures to the power line is between about 1 to about 20. Note that the lines and the power lines are identical.
- 18. Regarding claim 18, Kunikiyo shows that the each of the plurality of structures is alternatively spaced apart within the power line by a distance.
- 19. Regarding claim 20, Kunikiyo shows that the power line has a serpentine shape (e.g. fig. 9).
- 20. Regarding claim 21, Kunikiyo shows that the power line has a liner shape in the depth direction (e.g. fig. 12).

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### Claim Rejections - 35 USC § 103

21. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

- (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 22. This application currently names joint inventors. In considering patentability of the claims under 35 U.S.C. 103(a), the examiner presumes that the subject matter of the various claims was commonly owned at the time any inventions covered therein were made absent any evidence to the contrary. Applicant is advised of the obligation under 37 CFR 1.56 to point out the inventor and invention dates of each claim that was not commonly owned at the time a later invention was made in order for the examiner to consider the applicability of 35 U.S.C. 103(c) and potential 35 U.S.C. 102(e), (f) or (g) prior art under 35 U.S.C. 103(a).
- 23. Claim 7 and 16 are rejected under 35 U.S.C. 103(a) as being unpatentable over Kunikiyo (US 6,717,267).
- 24. Regarding claims 7 and 16, Kunikiyo teaches most aspects of the instant invention including an interconnection structure having a width (i.e., design variable col. 15/lls. 24-41), but does not disclose that the interconnect structure is from about 0.1 to 10 micrometers. Nonetheless, the specification contains no disclosure of either the critical nature of the claimed arrangement or any unexpected results arising therefrom. Where patentability is said to be based upon particular chosen dimensions or upon another variable recited in a claim, the applicant must show that the chosen dimensions

are critical. In re Woodruff, 919 F.2d 1575, 1578, 16 USPQ2d 1934, 1936 (Fed. Cir. 1990). Also, the specific width claimed by applicant, i.e., from about 0.1 to 10 micrometers, absent any criticality, is only considered to an optimum value of the interconnect width structure disclosed by the Prior Art that a person having ordinary skill in the art would have been able to determine using routine experimentation based, among other things, on the desired accuracy, manufacturing costs, etc. (see In re Boesch, 205 USPQ 215 (CCPA 1980)), and since neither non-obvious nor unexpected results, i.e., results which are different in kind and not in degree from the results of the prior art, will be obtained as long as an interconnect structure is used as already suggested by the Prior Art.

- 25. Claims 2 is rejected under 35 U.S.C. 103(a) as being unpatentable over Kunikiyo (US 6,717,267) in view of Khan et al. (US 6,853,070).
- 26. Regarding claim 2, Kunikiyo shows most aspects of the instant invention including a substrate but does not disclose a heat sink in contact with the substrate. Nevertheless, Khan (e.g. fig. 2A) shows a mounting structure including a heat sink 110/134 in contact with the substrate 102. According to Kahn this type of mounting structure provides an improved thermal, mechanical and electrical performance because the thermal stress is reduced due to a matched thermal coefficient (col. 1/lls. 52-67; col. 2/lls. 1-6 and col. 3/lls. 14-21). It would have been obvious to one of ordinary skill in the art at the time the invention was made to mount the device disclosed by Kunikiyo in the mounting structure disclosed by Khan which includes a heat sink in contact with the substrate to provide a semiconductor package having a reduce thermal

stress in order to improve the thermal, mechanical and electrical performance of the package.

### Response to Arguments

- 27. Applicant's arguments filed 03/20/2006 have been fully considered but they are not persuasive.
- 28. Although Applicant argues that the new limitations are not disclosed by the prior art Kunikiyo (e.g. fig. 12) shows that the interconnections (26a,b) are disposed near a power line 29A and are substantially enveloped by an insulating layer 23/10. Note that 29A is connected to a power supply by the plug 72 (col. 20/lls. 38-42 & 21/lls. 40-50).

#### Conclusion

- 29. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Leonardo Andújar whose telephone number is 571-272-1912. The examiner can normally be reached on Mon through Thu from 9:00 AM to 7:30 PM EST.
- 30. If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nathan J. Flynn can be reached on 571-272-1915. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.
- 31. Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should

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you have questions on access to the Private PAIR system, contact the Electronic

Business Center (EBC) at 866-217-9197 (toll-free).

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